

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	41	(US-20020056414-\$ or US-20020076490-\$ or US-20020146511-\$ or US-20020195056-\$ or US-20020197863-\$ or US-20020164849-\$).did. or (US-4423701-\$ or US-4430149-\$ or US-4664939-\$ or US-4949669-\$ or US-5292554-\$ or US-5384008-\$ or US-5433785-\$ or US-5518542-\$ or US-5620523-\$ or US-5676869-\$ or US-5725664-\$ or US-5759214-\$ or US-5772773-\$ or US-5785796-\$ or US-5916365-\$ or US-6017396-\$ or US-6017779-\$ or US-6031205-\$ or US-6143080-\$ or US-6143086-\$ or US-6174377-\$ or US-6176924-\$ or US-6178660-\$ or US-6187152-\$ or US-6281098-\$ or US-6310281-\$).did. or (US-6318945-\$ or US-6365025-\$ or US-6387185-\$ or US-6497767-\$ or US-6524952-\$ or US-6656273-\$ or US-6800173-\$ or US-6906008-\$ or US-6455098-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/08/24 16:39
L5	6	I4 and vacuum adj deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/24 16:41
L6	16	vacuum adj deposition and "700"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/24 16:43
L7	3	vacuum adj deposition adj chamber and "700"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/24 16:41
L8	16	I4 and vacuum with deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/24 16:47
L9	425	vacuum adj deposition and chamber same zone	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/24 16:47
L10	142	118/719.ccls. and vacuum adj deposition	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 16:55
L11	1536	atomic adj layer adj deposition and vacuum	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 16:55
L12	90	atomic adj layer adj deposition and vacuum adj deposition	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 16:55
S1	498	atomic adj layer adj deposition	US-PGPUB; USPAT	OR	ON	2005/03/07 11:30
S2	194	((atomic adj layer adj deposition) and chamber and region\$1	US-PGPUB; USPAT	OR	ON	2003/02/27 15:50
S3	94	((atomic adj layer adj deposition) and chamber and region\$1) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/02/27 16:43
S4	67	((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<="20010727") and wafer	US-PGPUB; USPAT	OR	ON	2003/02/27 15:51
S5	16	(((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<="20010727") and wafer) and support	US-PGPUB; USPAT	OR	ON	2003/02/27 15:51
S6	12	((((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<="20010727") and wafer) and support) and heater	US-PGPUB; USPAT	OR	ON	2005/03/04 12:54
S7	1	"5951776".pn.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:06
S8	1	"6525747".pn.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:40
S9	1	"6174805".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:36
S10	1	"6132514".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:36

S11	1	"6071552".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:37
S12	1	"5998871".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:37
S13	1	"5998871".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:37
S14	1	"5972785".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:37
S15	1	"5916365".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:37
S16	1	"5416045".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:38
S17	1	"5344792".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:38
S18	1	"6190732".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:39
S19	1	"6174377".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:39
S20	1	"5935338".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:40
S21	1	"5879459".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:40
S22	1	"5582866".PN.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:40
S23	655	700/121.ccls.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:40
S24	213	700/121.ccls. and deposition	US-PGPUB; USPAT	OR	ON	2003/02/27 16:41
S25	113	(700/121.ccls. and deposition) and chamber	US-PGPUB; USPAT	OR	ON	2003/02/27 16:41
S26	90	((700/121.ccls. and deposition) and chamber) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/03/03 14:47
S27	3	((((700/121.ccls. and deposition) and chamber) and @ad<="20010727") and piston	US-PGPUB; USPAT	OR	ON	2003/02/27 16:41
S28	1	((((atomic adj layer adj deposition) and chamber and region\$1) and @ad<="20010727") and piston	US-PGPUB; USPAT	OR	ON	2003/02/27 16:50
S29	1228	118/719.ccls.	US-PGPUB; USPAT	OR	ON	2003/02/27 16:50
S30	55	118/719.ccls. and wafer and piston	US-PGPUB; USPAT	OR	ON	2003/02/27 16:50
S31	16	(118/719.ccls. and wafer and piston) and aperture	US-PGPUB; USPAT	OR	ON	2003/02/27 16:51
S32	15	kosowski.xa.	US-PGPUB; USPAT	OR	ON	2003/03/03 14:05
S33	4183	deposition and wafer and support and chamber and region\$2 and temperature and two and gas	US-PGPUB; USPAT	OR	ON	2003/03/03 14:47
S34	3626	(deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/03/03 17:34
S35	167	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727") and piston	US-PGPUB; USPAT	OR	ON	2003/03/03 14:50
S36	11	((((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727") and piston) and monolayer	US-PGPUB; USPAT	OR	ON	2003/03/03 14:51
S37	90	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727") and atomic adj layer	US-PGPUB; USPAT	OR	ON	2003/03/03 14:51

S38	1413684	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727") and atomic adj layer) and deposition near\$5 region\$1	US-PGPUB; USPAT	OR	ON	2003/03/03 14:53
S39	90	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727") and atomic adj layer) and (deposition near\$5 region\$1)	US-PGPUB; USPAT	OR	ON	2003/03/03 16:18
S40	1	"6174805".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 15:11
S41	1	"6132514".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 15:11
S42	1	"6071552".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 15:11
S43	1	"5998871".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 15:11
S44	4	((deposition and wafer and support and chamber and region\$2 and temperature and two and gas) and @ad<="20010727") and moveable adj support	US-PGPUB; USPAT	OR	ON	2003/03/03 16:35
S45	64	deposition and moveable adj support	US-PGPUB; USPAT	OR	ON	2003/03/03 16:35
S46	62	(deposition and moveable adj support) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/03/03 16:37
S47	25	((deposition and moveable adj support) and @ad<="20010727") and wafer	US-PGPUB; USPAT	OR	ON	2003/03/03 17:16
S48	1	"5013400".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 16:45
S49	1	"4990374".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 16:45
S50	1	"4978412".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 16:46
S51	1	"4963713".PN.	US-PGPUB; USPAT	OR	ON	2003/03/03 16:46
S52	655	700/121.cds.	US-PGPUB; USPAT	OR	ON	2003/03/03 17:16
S53	2	700/121.cds. and atomic adj layer adj deposition	US-PGPUB; USPAT	OR	ON	2003/03/03 17:33
S54	21	interconnected with deposition with region\$2	US-PGPUB; USPAT	OR	ON	2003/03/03 17:33
S55	21	(interconnected with deposition with region\$2) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/03/04 10:10
S56	1	"4423701".pn.	US-PGPUB; USPAT	OR	ON	2003/03/04 10:10
S57	1	"4423701".pn. and (heater or temperature)	US-PGPUB; USPAT	OR	ON	2003/03/04 11:13
S58	9	(US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.	US-PGPUB; USPAT	OR	OFF	2003/03/04 13:26
S59	2	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.) and aperture	US-PGPUB; USPAT	OR	ON	2003/03/04 13:51
S60	0	"4423701".pn. and gase	US-PGPUB; USPAT	OR	ON	2003/03/04 13:51
S61	1	"4423701".pn. and gas	US-PGPUB; USPAT	OR	ON	2003/03/04 13:51
S62	1	"4664939".pn. and gas	US-PGPUB; USPAT	OR	ON	2003/03/04 14:09

S63	2	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.) and electrostatic	US-PGPUB; USPAT	OR	ON	2003/03/04 14:18
S64	0	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4423701-\$ or US-4664939-\$).did. or (US-20020197863-\$ or US-20020076490-\$ or US-20020056414-\$).did.) and piston	US-PGPUB; USPAT	OR	ON	2003/03/04 14:18
S65	18	atomic adj layer adj deposition and piston	US-PGPUB; USPAT	OR	ON	2003/03/04 14:22
S66	437	deposition and chamber and support and wafer and piston	US-PGPUB; USPAT	OR	ON	2003/03/04 14:23
S67	242	(deposition and chamber and support and wafer and piston) and region and gas	US-PGPUB; USPAT	OR	ON	2003/03/04 14:23
S68	191	((deposition and chamber and support and wafer and piston) and region and gas) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/03/04 14:25
S69	94	deposition and wafer adj support and piston	US-PGPUB; USPAT	OR	ON	2003/03/04 14:25
S70	83	(deposition and wafer adj support and piston) and @ad<="20010727"	US-PGPUB; USPAT	OR	ON	2003/03/04 14:26
S71	8	((deposition and wafer adj support and piston) and @ad<="20010727") and wafer adj support with piston	US-PGPUB; USPAT	OR	ON	2003/03/04 14:28
S72	1	"5228502".pn.	US-PGPUB; USPAT	OR	ON	2003/03/04 14:28
S73	10	(US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$).did. or (US-20020076490-\$ or US-20020197863-\$ or US-20020056414-\$).did.	US-PGPUB; USPAT	OR	OFF	2003/07/25 14:05
S74	1	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$).did. or (US-20020076490-\$ or US-20020197863-\$ or US-20020056414-\$).did.) and elevation	US-PGPUB; USPAT	OR	ON	2003/07/25 14:06
S75	8	((US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-5292554-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$).did. or (US-20020076490-\$ or US-20020197863-\$ or US-20020056414-\$).did.) and vertical	US-PGPUB; USPAT	OR	ON	2003/07/25 14:11
S76	58	dworkin.in.	US-PGPUB; USPAT	OR	ON	2003/07/28 11:14
S77	1	dworkin.in. and vendor	US-PGPUB; USPAT	OR	ON	2003/07/28 11:56
S78	20721	image adj planes	US-PGPUB; USPAT	OR	ON	2003/07/28 11:56
S79	1159	(image adj planes) and "345"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2003/07/28 11:56
S80	680	118/729.ccls.	US-PGPUB; USPAT	OR	ON	2003/11/17 16:10
S81	411	118/729.ccls. and (vertical or elevation)	US-PGPUB; USPAT	OR	ON	2003/11/17 16:10
S82	306	(118/729.ccls. and (vertical or elevation)) and deposition	US-PGPUB; USPAT	OR	ON	2003/11/17 16:10
S83	50	((118/729.ccls. and (vertical or elevation)) and deposition) and chuck	US-PGPUB; USPAT	OR	ON	2003/11/17 16:10
S84	48	((((118/729.ccls. and (vertical or elevation)) and deposition) and chuck) and (zone or chamber)	US-PGPUB; USPAT	OR	ON	2003/11/17 16:11
S85	12	(((((118/729.ccls. and (vertical or elevation)) and deposition) and chuck) and (zone or chamber)) and pedestal	US-PGPUB; USPAT	OR	ON	2003/11/17 16:16

S86	9	(((((118/729.cds. and (vertical or elevation)) and deposition) and chuck) and (zone or chamber)) and pedestal) and (((118/729.cds. and (vertical or elevation)) and deposition) and (pedestal same vertical\$3))	US-PGPUB; USPAT	OR	ON	2003/11/17 16:19
S87	32	((118/729.cds. and (vertical or elevation)) and deposition) and (pedestal same vertical\$3)	US-PGPUB; USPAT	OR	ON	2003/11/17 16:50
S88	1	"6143086".URPN.	USPAT	OR	ON	2003/11/17 16:27
S89	16	("3306768" "3641974" "4724621" "4938815" "5065698" "5094885" "5135629" "5169684" "5192371" "5213650" "5228501" "5238499" "5304249" "5474612" "5589224" "5803977").PN.	USPAT	OR	ON	2003/11/17 16:27
S90	225	(wafer or semiconductor) and (pedestal same vertical\$4) and (mult\$4 near\$5 chamber\$2)	US-PGPUB; USPAT	OR	ON	2003/11/17 16:51
S91	209	((wafer or semiconductor) and (pedestal same vertical\$4) and (mult\$4 near\$5 chamber\$2)) and deposition	US-PGPUB; USPAT	OR	ON	2003/11/17 16:51
S92	16	"5855675".URPN.	USPAT	OR	ON	2003/11/17 16:52
S93	37	((wafer or semiconductor) and (pedestal same vertical\$4) and (mult\$4 near\$5 chamber\$2)) and deposition) and chuck and heater	US-PGPUB; USPAT	OR	ON	2003/11/18 10:02
S94	25	"5909994".URPN.	USPAT	OR	ON	2003/11/18 09:55
S95	58	(wafer or semiconductor) and vertical and multichamber and deposition and chuck and heater	US-PGPUB; USPAT	OR	ON	2003/11/18 10:03
S96	66	(wafer or semiconductor) and vertical and multichamber and deposition and chuck	US-PGPUB; USPAT	OR	ON	2003/11/18 10:03
S97	201	(wafer or semiconductor) and vertical and multichamber and deposition	US-PGPUB; USPAT	OR	ON	2003/11/18 10:03
S98	172	((wafer or semiconductor) and vertical and multichamber and deposition) and (pedestal or support)	US-PGPUB; USPAT	OR	ON	2003/11/18 10:04
S99	11	((wafer or semiconductor) and vertical and multichamber and deposition) and (pedestal or support)) and "700"/\$.cds.	US-PGPUB; USPAT	OR	ON	2003/11/18 10:05
S10 0	2	"6178660".URPN.	USPAT	OR	ON	2003/11/18 10:12
S10 1	13	("4795299" "4917556" "5228206" "5423971" "5529657" "5611861" "5755938" "5759334" "5855675" "5863170" "5880924" "5882165" "5886864").PN.	USPAT	OR	ON	2003/11/18 10:13
S10 2	1	"4423701".pn.	US-PGPUB; USPAT	OR	ON	2003/11/18 10:23
S10 3	1	"4423701".pn. and vertical	US-PGPUB; USPAT	OR	ON	2003/11/18 10:23
S10 4	15	(US-4423701-\$ or US-5292554-\$ or US-5518542-\$ or US-4664939-\$ or US-6524952-\$ or US-6387185-\$ or US-5916365-\$ or US-6143086-\$ or US-6497767-\$ or US-6178660-\$ or US-5772773-\$ or US-6318945-\$).did. or (US-20020056414-\$ or US-20020197863-\$ or US-20020076490-\$).did.	US-PGPUB; USPAT	OR	OFF	2003/11/18 10:40
S10 5	51	multizone and deposition and wafer	US-PGPUB; USPAT	OR	ON	2003/11/18 10:45
S10 6	25	(multizone and deposition and wafer) and vertical	US-PGPUB; USPAT	OR	ON	2003/11/18 10:40
S10 7	4	((multizone and deposition and wafer) and vertical) and pedestal	US-PGPUB; USPAT	OR	ON	2003/11/18 10:42
S10 8	1	"6352593".pn.	US-PGPUB; USPAT	OR	ON	2003/11/18 10:42
S10 9	220	(multizone or multi-zone) and deposition and wafer	US-PGPUB; USPAT	OR	ON	2003/11/18 10:46
S11 0	0	((multizone or multi-zone) and deposition and wafer) and verticle	US-PGPUB; USPAT	OR	ON	2003/11/18 10:46
S11 1	126	((multizone or multi-zone) and deposition and wafer) and vertical	US-PGPUB; USPAT	OR	ON	2003/11/18 10:46

S11 2	104	((((multizone or multi-zone) and deposition and wafer) and vertical) and (support or pedestal)	US-PGPUB; USPAT	OR	ON	2003/11/18 10:46
S11 3	63	((((multizone or multi-zone) and deposition and wafer) and vertical) and (support or pedestal)) and heater	US-PGPUB; USPAT	OR	ON	2003/11/18 10:46
S11 4	27	(((((multizone or multi-zone) and deposition and wafer) and vertical) and (support or pedestal)) and heater) and chuck	US-PGPUB; USPAT	OR	ON	2003/11/18 11:12
S11 5	2	"6413321".URPN.	USPAT	OR	ON	2003/11/18 10:50
S11 6	17	("3627590" "4798165" "5045346" "5221414" "5230741" "5238499" "5244730" "5350427" "5366585" "5374594" "5447570" "5589233" "5614055" "5855681" "5871811" "5879128" "6020035").PN.	USPAT	OR	ON	2003/11/18 10:50
S11 7	1329	118/719.ccls.	US-PGPUB; USPAT	OR	ON	2003/11/18 11:12
S11 8	73	118/719.ccls. and pedestal and vertical	US-PGPUB; USPAT	OR	ON	2003/11/18 12:47
S11 9	450	118/719.ccls. and (pedestal or support) and vertical	US-PGPUB; USPAT	OR	ON	2003/11/18 11:13
S12 0	25	(118/719.ccls. and pedestal and vertical) and zone and gas	US-PGPUB; USPAT	OR	ON	2003/11/18 12:55
S12 1	253	118/719.ccls. and aperture	US-PGPUB; USPAT	OR	ON	2003/11/18 12:55
S12 2	171	(118/719.ccls. and aperture) and vertical\$3	US-PGPUB; USPAT	OR	ON	2003/11/18 12:55
S12 3	112	((118/719.ccls. and aperture) and vertical\$3) and wafer	US-PGPUB; USPAT	OR	ON	2003/11/18 12:55
S12 4	56	((((118/719.ccls. and aperture) and vertical\$3) and wafer) and (region or zone)	US-PGPUB; USPAT	OR	ON	2003/11/18 12:57
S12 5	3	(((((118/719.ccls. and aperture) and vertical\$3) and wafer) and (region or zone)) and piston	US-PGPUB; USPAT	OR	ON	2003/11/18 13:26
S12 6	30	"4430149".URPN.	USPAT	OR	ON	2003/11/18 13:13
S12 7	823	700/121.ccls.	US-PGPUB; USPAT	OR	ON	2003/11/18 13:27
S12 8	257	700/121.ccls. and deposition and wafer	US-PGPUB; USPAT	OR	ON	2003/11/18 13:27
S12 9	11	(700/121.ccls. and deposition and wafer) and zone and aperture	US-PGPUB; USPAT	OR	ON	2003/11/18 13:27
S13 0	44138	"438"/\$.ccls. and deposition	US-PGPUB; USPAT	OR	ON	2003/11/18 13:30
S13 1	12	("438"/\$.ccls. and deposition) and pedestal and piston	US-PGPUB; USPAT	OR	ON	2003/11/18 13:34
S13 2	607	438/680.ccls.	US-PGPUB; USPAT	OR	ON	2003/11/18 13:36
S13 3	10	deposition and wafer adj support and (multizone or multi-zone) and aperture and vertical\$4 and heat\$4	US-PGPUB; USPAT	OR	ON	2003/11/18 13:39
S13 4	4	cvd and pedestal same piston	US-PGPUB; USPAT	OR	ON	2003/11/18 13:48
S13 5	17	("4382739" "4513855" "4590380" "4619573" "4632624" "4746256" "4801241" "4861222" "4872947" "4894132" "4902531" "4915564" "4923584" "5051054" "5098198" "5108570" "5131460").PN.	USPAT	OR	ON	2003/11/18 13:40
S13 6	607	438/680.ccls.	US-PGPUB; USPAT	OR	ON	2003/11/18 13:48
S13 7	26	438/680.ccls. and wafer adj support	US-PGPUB; USPAT	OR	ON	2003/11/18 14:04
S13 8	25	438/680.ccls. and vertical and pedestal	US-PGPUB; USPAT	OR	ON	2003/11/18 14:04

S13 9	19	(438/680.cds. and vertical and pedestal) not (438/680.cds. and wafer adj support)	US-PGPUB; USPAT	OR	ON	2003/11/18 14:09
S14 0	8	("4951601" "5246881" "5366585" "5516367" "5558717" "5846332" "5853607" "5885356").PN.	USPAT	OR	ON	2003/11/18 14:06
S14 1	2	"6063441".URPN.	USPAT	OR	ON	2003/11/18 14:08
S14 2	323	438/478.cds.	US-PGPUB; USPAT	OR	ON	2003/11/18 14:09
S14 3	14	438/478.cds. and pedestal	US-PGPUB; USPAT	OR	ON	2003/11/18 14:12
S14 4	690	wafer and deposition and support same screw and vertical	US-PGPUB; USPAT	OR	ON	2003/11/18 14:12
S14 5	245	(wafer and deposition and support same screw and vertical) and cvd	US-PGPUB; USPAT	OR	ON	2003/11/18 14:12
S14 6	123	((wafer and deposition and support same screw and vertical) and cvd) and heater	US-PGPUB; USPAT	OR	ON	2003/11/18 14:13
S14 7	47	((((wafer and deposition and support same screw and vertical) and cvd) and heater) and zone	US-PGPUB; USPAT	OR	ON	2003/11/18 14:20
S14 8	24	"5620523".URPN.	USPAT	OR	ON	2003/11/18 14:20
S14 9	38	deposition and wafer and ball adj screw and zone	US-PGPUB; USPAT	OR	ON	2003/11/18 14:31
S15 0	275	cvd and ball adj screw	US-PGPUB; USPAT	OR	ON	2003/11/18 14:31
S15 1	6	(cvd and ball adj screw) and zone and aperture	US-PGPUB; USPAT	OR	ON	2003/11/18 14:31
S15 2	0	"6497767".URPN.	USPAT	OR	ON	2003/11/18 15:14
S15 3	10	("5273588" "5418885" "5446825" "5688331" "5796074" "5855675" "5916370" "6001183" "6190113" "6190460").PN.	USPAT	OR	ON	2003/11/18 15:15
S15 4	1	"6497767".pn.	US-PGPUB; USPAT	OR	ON	2003/11/18 16:30
S15 5	1	"6650315".pn.	US-PGPUB; USPAT	OR	ON	2003/11/18 16:49
S15 6	1	"6650346".pn.	US-PGPUB; USPAT	OR	ON	2003/11/18 16:50
S15 7	46	("6630030" or "6579372" or "6578287" or "6572705" or "6551406" or "6511539" or "6481945" or "6478872" or "6447607" or "6306216" or "6305314" or "6270572" or "6231672" or "6200893" or "6197683" or "6183563" or "6174377" or "6139700" or "6042652" or "6015590" or "5916365" or "5879459" or "5855680" or "5835677" or "5807792" or "5796116" or "5730802" or "5711811" or "5674786" or "5503875" or "5483919" or "5480818" or "5443647" or "5441703" or "5374570" or "5338362" or "5294286" or "5281274" or "5261959" or "5225366" or "4993357" or "4975252" or "4834831" or "4413022" or "4389973" or "4058430").pn.	US-PGPUB; USPAT	OR	ON	2004/09/16 14:17
S15 8	20	(US-6143086-\$ or US-5772773-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$ or US-5292554-\$ or US-6387185-\$ or US-6524952-\$ or US-5916365-\$ or US-6497767-\$ or US-6178660-\$ or US-6318945-\$ or US-4430149-\$ or US-4949669-\$ or US-5676869-\$ or US-5620523-\$ or US-6017396-\$).did. or (US-20020056414-\$ or US-20020197863-\$ or US-20020076490-\$).did.	US-PGPUB; USPAT	OR	OFF	2004/09/16 16:46

S15 9	10	((US-6143086-\$ or US-5772773-\$ or US-4664939-\$ or US-4423701-\$ or US-5518542-\$ or US-5292554-\$ or US-6387185-\$ or US-6524952-\$ or US-5916365-\$ or US-6497767-\$ or US-6178660-\$ or US-6318945-\$ or US-4430149-\$ or US-4949669-\$ or US-5676869-\$ or US-5620523-\$ or US-6017396-\$).did. or (US-20020056414-\$ or US-20020197863-\$ or US-20020076490-\$).did.) and purge	US-PGPUB; USPAT	OR	ON	2004/09/16 16:46
S16 0	3	"5916365".pn. or "4423701".pn. or "6497767".pn.	US-PGPUB; USPAT	OR	ON	2004/09/17 12:45
S16 2	2553	atomic adj layer adj deposition	US-PGPUB; USPAT	OR	ON	2005/03/04 12:53
S16 3	178	S162 and chamber and region\$ and wafer and support and heater	US-PGPUB; USPAT	OR	ON	2005/03/04 12:54
S16 4	18	S163 and region\$2 same (connected or interconnected)	US-PGPUB; USPAT	OR	ON	2005/03/04 12:57
S16 5	115	S163 not applied.as.	US-PGPUB; USPAT	OR	ON	2005/03/04 12:57
S16 6	84	S165 and vertical\$4	US-PGPUB; USPAT	OR	ON	2005/03/04 13:12
S16 7	1	"6174377".pn.	US-PGPUB; USPAT	OR	ON	2005/03/04 13:00
S16 8	48	("5078851" "5156820" "5294778" "5582866" "5855675" "5935338").PN. OR ("6174377").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/04 13:04
S16 9	42	("6174377").URPN.	USPAT	OR	OFF	2005/03/04 13:04
S17 0	23	S169 and vertical\$4	USPAT	OR	OFF	2005/03/04 13:04
S17 1	6	("5078851" "5156820" "5294778" "5582866" "5855675" "5935338").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/04 13:10
S17 2	67	S165 and vertical\$4 same (support or pedestal)	US-PGPUB; USPAT	OR	ON	2005/03/04 13:19
S17 3	87	ladder adj boat	US-PGPUB; USPAT	OR	ON	2005/03/04 13:19
S17 4	8	S173 and (ald or cvd)	US-PGPUB; USPAT	OR	ON	2005/03/04 13:50
S17 5	0	("6656273").URPN.	USPAT	OR	OFF	2005/03/04 13:26
S17 6	7	("5433785" "5565034" "5725664" "5759214" "6113694" "6261365" "6350316").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/03/04 13:26
S17 7	13	ring adj boat and (ald or cvd)	US-PGPUB; USPAT	OR	ON	2005/03/04 13:56
S17 8	87800	(ald or cvd)	US-PGPUB; USPAT	OR	ON	2005/03/04 13:56
S17 9	3603	S178 and vertical\$3 same (support or pedestal)	US-PGPUB; USPAT	OR	ON	2005/03/04 13:57
S18 0	1690	S179 and chamber same vertical\$4	US-PGPUB; USPAT	OR	ON	2005/03/04 13:57
S18 1	677	S180 and "118"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2005/03/04 13:57
S18 2	315	S181 and process adj chamber	US-PGPUB; USPAT	OR	ON	2005/03/04 13:57
S18 3	191	S182 and vertical\$4 near5 (pedestal or support)	US-PGPUB; USPAT	OR	ON	2005/03/04 13:58
S18 4	92	S183 not applied.as.	US-PGPUB; USPAT	OR	ON	2005/03/04 14:38

S18 5	1	"6187152".pn.	US-PGPUB; USPAT	OR	ON	2005/03/04 14:39
S18 6	7120	118/715,719,729.cds. or 205/80.cds.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/04 15:33
S18 7	1	"6497676".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/04 15:57
S18 8	30	(US-20020056414-\$ or US-20020076490-\$ or US-20020197863-\$).did. or (US-4423701-\$ or US-4430149-\$ or US-4664939-\$ or US-4949669-\$ or US-5292554-\$ or US-5518542-\$ or US-5620523-\$ or US-5676869-\$ or US-5772773-\$ or US-5916365-\$ or US-6017396-\$ or US-6143086-\$ or US-6178660-\$ or US-6318945-\$ or US-6387185-\$ or US-6497767-\$ or US-6524952-\$ or US-6174377-\$ or US-6800173-\$ or US-6656273-\$ or US-5759214-\$ or US-5433785-\$ or US-5725664-\$ or US-6031205-\$ or US-6365025-\$ or US-6187152-\$).did. or (US-5785796-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/03/04 17:04
S18 9	18	S188 and horizontal\$4	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/04 17:16
S19 0	12	vertical adj furnace and multi-zone	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/04 17:18
S19 1	1	"6365025".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/03/04 17:19
S19 3	1	"20030023338"	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/06/08 13:10
S19 4	1269	vacuum adj deposition adj chamber	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 14:21
S19 5	8	S194 and wafer with support with vertical\$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:16
S19 6	1	S195 and zone	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:16
S19 7	214	S194 and zone	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:16
S19 8	104	S197 and zone same deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:16
S19 9	76	S197 and zone with deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:16
S20 0	12	S197 and zone\$1 with deposition with multiple	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:21
S20 1	16	vertical adj furnace and vacuum adj deposition	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:31
S20 2	1	"6017779".pn.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:22
S20 3	0	("6906008").URPN.	USPAT	OR	OFF	2005/08/23 13:29

S20 4	7	("3829373" "3884787" "4562093" "4763601" "5968877" "6673387").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 13:29
S20 5	81	vacuum adj deposition and elevat\$3 with wafer	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:56
S20 6	60	S205 and gas	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:56
S20 7	44	S206 and (chamber or zone)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 13:57
S20 8	5	vacuum adj deposition adj zone	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 14:22
S20 9	41	vacuum adj deposition and multiple near3 zone\$1	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 14:23
S21 0	12	S209 and (wafer or substrate) with support	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/08/23 14:23
S21 1	8	("3006737" "3020129" "4154870" "4910163" "5810934" "6110290").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 15:21
S21 2	0	("6281098").URPN.	USPAT	OR	OFF	2005/08/23 15:33
S21 3	4	"917842"	USPAT	OR	OFF	2005/08/23 15:34
S21 4	0	"20030023338"	USPAT	OR	OFF	2005/08/23 15:34
S21 5	1	"0023338"	USPAT	OR	OFF	2005/08/23 15:34
S21 6	1	"20030023338"	US-PGPUB; USPAT	OR	OFF	2005/08/23 15:35
S21 7	47	deposition adj region\$1 with multiple	US-PGPUB; USPAT	OR	OFF	2005/08/23 16:07
S21 8	1	S216 and monolayer	US-PGPUB; USPAT	OR	OFF	2005/08/23 15:39
S21 9	1	"6383989".pn.	US-PGPUB; USPAT	OR	OFF	2005/08/23 16:07
S22 0	4	("5850071" "6051371" "6117266" "6214706").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:19
S22 1	739	chemisor\$5 and monolayer and (wafer or substrate) and (support or pedestal)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:20
S22 2	498	S221 and vacuum and deposition	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 10:40
S22 3	55	S222 and (vertical or elevat\$3) with (pedestal or platform or support)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:24
S22 4	13	US-6630201-\$.DID. OR US-6660126-\$.DID. OR US-6716287-\$.DID. OR US-6718126-\$.DID. OR US-6734020-\$.DID. OR US-6772072-\$.DID. OR US-6773507-\$.DID. OR US-6777352-\$.DID. OR US-6778762-\$.DID. OR US-6818094-\$.DID. OR US-6821563-\$.DID. OR US-6866746-\$.DID. OR US-6868859-\$.DID.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:26

S22 5	7	"20010014371" "20010013312" "20010042523" "20010054377" "20020000196" "20020009544"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:27
S22 6	22	"20020007790" "20020041931" "20020052097" "20020066411" "20020076508" "20020076507" "20020076481" "20020073924" "20020086106" "20020094689" "20020092471" "20020104481" "20020108570" "20020121342" "20020121241" "20020127745" "20020134307" "20020146511" "20020144657" "20020144655"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:29
S22 7	28	"20030224723" "20030010451" "20030022338" "20030042630" "20030053799" "20030057527" "20030072913" "20030075925" "20030075273" "20030079686" "20030089308" "20030101927" "20030106490" "20030113187" "20030116087" "20030121608" "20030121469" "20030143747" "20030143328" "20030140854"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:30
S22 8	21	"20030153177" "20030172872" "20030194493" "20030198754" "20030216981" "20030213560" "20030221780" "20030224107" "20040015300" "20040014320" "20040013577" "20040011504" "20040011404" "20040016404" "20040025370" "20040065255" "20040071897" "20040069227" "20040144311" "20040144308" "20050006799"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:31
S22 9	91	S224 or S225 or S226 or S227 or S228	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:31
S23 0	3	S229 and piston	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:32
S23 1	1	S230 and (zone with deposition)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:33
S23 2	1650	118/719.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 16:47
S23 3	100	S232 and piston	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:33
S23 4	3	S233 and monolayer	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:34
S23 5	1	S234 and (vertical or elevat\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/23 17:34
S23 6	62	vacuum and deposition and (raised and lowered) same wafer adj support	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 10:41
S23 7	8936	vacuum and deposition and (raised and lowered) withwafer adj support	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 10:41
S23 8	34	vacuum and deposition and (raised and lowered) with wafer adj support	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 10:43
S23 9	1	"6455098".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/08/24 10:44